

# Editorial

**Mr. Delip “Doug” Bokil, Editor-in-Chief**

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Welcome to the fourth quarterly issue of year 2005.

It is difficult for me to imagine that I have had the fabulous challenge and opportunity of being the EIC of JMEP for the past two years - time flies when you are having fun!

It is our pleasure to introduce to you three new Associate Editors who have joined our Editorial board. (1) Prof. K N Seetharamu, M S Ramaiah School of Advance Studies, Bangalore, India, (2) Dr. Andrzej Dziedzic, Wroclaw University of Technology, Poland and (3) Mr. Ziliang Wang, Professor of Electronics Packaging with Nanjing Electronic Devices Institute, PRC.

In this issue we have two issues on MEMS applications, one on thermal analysis, and one on non-destructive testing, two on general aspects of plastic packaging and one that revisits Au-Sn intermetallic - something that I first encountered when we were developing Au thermo-sonic wire bonding at RCA during the late 1970s!

'Tis the season to be jolly - so, a "Merry Christmas, Hanukkah, Kwanzaa and a Happy New Year to all!"

Those wishing to submit papers to JMEP should pay close attention to the formatting requirements that are documented at this link: <http://www.imaps.org/jmep/authors.htm>. Close adherence to these guidelines will result in expediting the whole publication process.

Regards,  
Delip "Doug" Bokil  
Editor-in-Chief